Materials Declaration

Package	LQFP
Body Size	20 X 20
LeadCount	144
Option	Pb Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	8	3.14 E-02	27252
SiO2 Filler	86	3.38 E-01	292963
Phenol Resin	5	1.97 E-02	17033
Antimony_Sb2O3	0.4	1.57 E-03	1363
Brominated Resin	0.4	1.57 E-03	1363
Carbon Black	0.2	7.86 E-04	681

Molding Compound

Item	PPM	Method
Pb	<2.0	EPA method #3052 (ICPAES)
Cd	<2.0	BS EN 1122:2001B (ICP AES)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)
PBB	ND	SGS in-house Method by GC/MS
PBDE	ND	SGS in-house Method by GC/MS

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	4.22 E-01	365618
Ni	3	1.32 E-02	11402
Si	0.65	2.85 E-03	2470
Mg	0.15	6.58 E-04	570

Die Attach Paste

Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	<5.0	EPA method 7196A & EPA 3060A

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	2.90 E-03	2513

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	8.60 E-03	7453

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	3.94 E-03	3414

Chip

	% of Chip	Weight (g)	PPM
Si	100	2.80 E-01	242698

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	26	6.96 E-03	6034
Ag Filler	74	1.98 E-02	17172

Package Totals

Weight (g)	PPM
1.15 E+00	1000000

STS-ST-C

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary

5/31/04

Materials Declaration

Package	LQFP
Body Size	20 X 20
LeadCount	144
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	8	3.14 E-02	27252
SiO2 Filler	86	3.38 E-01	292963
Phenol Resin	5	1.97 E-02	17033
Antimony_Sb2O3	0.4	1.57 E-03	1363
Brominated Resin	0.4	1.57 E-03	1363
Carbon Black	0.2	7.86 E-04	681

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	4.22 E-01	365618
Ni	3	1.32 E-02	11402
Si	0.65	2.85 E-03	2470
Mg	0.15	6.58 E-04	570

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	2.90 E-03	2513

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	7.31 E-03	6335
Pb	15	1.29 E-03	1118

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	3.94 E-03	3414

Chip

	% of Chip	Weight (g)	PPM
Si	100	2.80 E-01	242698

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	26	6.96 E-03	6034
Ag Filler	74	1.98 E-02	17172

Package Totals

Weight (g)	PPM
1.15 E+00	1000000

Molding Compound

Item	PPM	Method
Pb	<2.0	EPA method #3052 (ICPAES)
Cd	<2.0	BS EN 1122:2001B (ICP AES)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)
PBB	ND	SGS in-house Method by GC/MS
PBDE	ND	SGS in-house Method by GC/MS

Die Attach Paste

Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	<5.0	EPA method 7196A & EPA 3060A

STS-ST-A

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ANALOG DEVICES

ADI Proprietary

5/31/04